



Micro Commercial Components  
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# DL5711

## Schottky Barrier Switching Diode

### Features

- Fast Switching Speed
- High Reverse Breakdown Voltage
- Low Forward Voltage Drop
- For General Purpose Application

### Mechanical Data

- Case: Minimelf, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Indicated by Cathode Band
- Weight: 0.05 grams ( approx.)

Maximum Ratings @ 25°C Unless Otherwise Specified

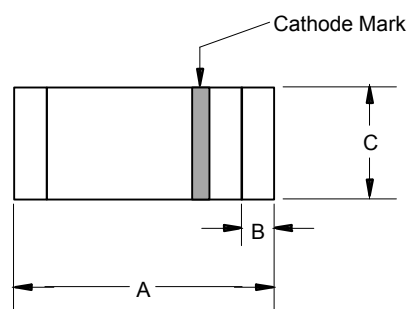
Characteristic	Symbol	Value	Unit
Peak Reverse Voltage	$V_{RRM}$	60	V
Forward Continuous Current(Note1)	$I_{FM}$	15	mA
Maximum Single cycle surge 10us square wave	$I_{FSM}$	2.0	A
Power Dissipation(Note 1)	$P_d$	400	mW
Thermal Resistance(Note 1)	$R_{\theta JA}$	0.3	K/mW
Operation/Storage Temp. Range	$T_j, T_{STG}$	-55 to 150	°C

Electrical Characteristics @ 25°C Unless Otherwise Specified

Characteristic	Symbol	Min	Max	Unit	Test Cond.
Reverse Breakdown Volt.	$V_{(BR)R}$	70	-----	V	$I_R=10\mu A$
Reverse Leakage Current.	$I_R$	-----	200	nA	$V_R=50V$
Forward Volt. Drop	$V_F$	-----	0.41 1	V	$I_F=1.0mA$ $I_F=15mA$
Junction Capacitance	$C_j$	-----	2.0	pF	$V_R=0V, f=1.0MHz$
Reverse Recovery Time	$t_{rr}$	-----	1.0	ns	$I_F=I_R=5mA,$ $I_{rr}=0.1 \times I_R$ $R_L=100\Omega$

**Note:** 1. Valid provided that electrodes are kept at ambient temperature

### MINIMELF



DIM	DIMENSION				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.134	.142	3.40	3.60	
B	.008	.016	0.20	0.40	
C	.055	.059	1.40	1.50	

### SUGGESTED SOLDER PAD LAYOUT

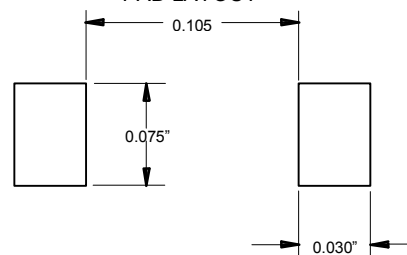


Fig.1 Typical variation of fwd. current vs forward. voltage for primary conduction through the Schottky barrier

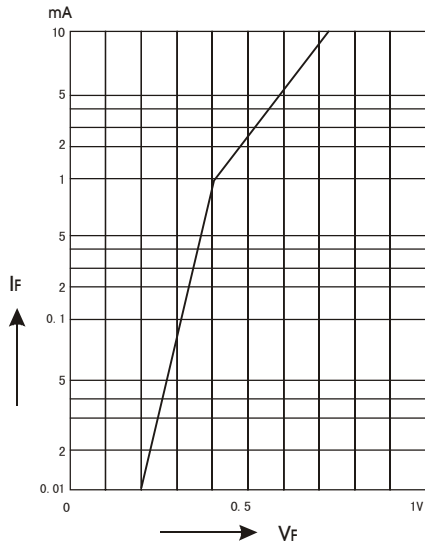


Fig.2 Typical forward conduction curve of combination Schottky barrier and PN junction guard ring

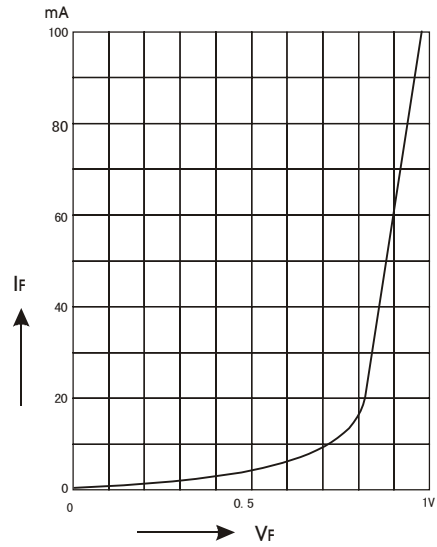


Fig.3 Typical variation of reverse current at various temperatures

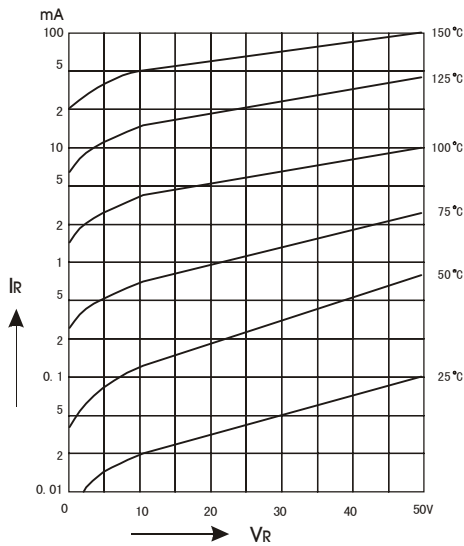


Fig.4 Typical capacitance curve as a function of reverse voltage

